COMPONENTS MARKED ‘DNP’ SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: TIDA-01559</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
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<td>TID #: TIDA-01559</td>
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<td>PLOT NAME = Top Assembly Drawing</td>
<td>GENERATED : 2018/5/29 14:48:24</td>
<td>TEXAS INSTRUMENTS</td>
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